



PRODUCT DATA SHEET



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Datasheet



Resources

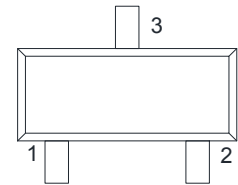


Samples

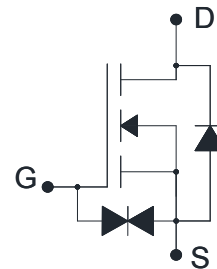
Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Features

- 60V, $R_{DS(ON)}=1.5\Omega$ (Typ), $V_{GS}=10V$
 $R_{DS(ON)}=2.4\Omega$ (Typ), $V_{GS}=4.5V$
- Use trench MOSFET technology
- High density cell design for low $R_{DS(on)}$
- Material: Halogen free
- Reliable and rugged
- Avalanche Rated
- Low leakage current



- 1 Gate
- 2 Source
- 3 Drain



Applications

- PWM applications
- Load switch
- Power management in portable/desktop PCs
- DC/DC conversion

Absolute Maximum Rating & Thermal Characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		BV_{DSS}	60	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current	$T_A=25^\circ C$	I_D	0.38	A
	$T_A=100^\circ C$		0.25	
Maximum Power Dissipation		P_D	350	mW
Pulsed Drain Current ^a		I_{DM}	1.5	A
Operating Junction Temperature		T_J	150	°C
Lead Temperature		T_L	260	°C
Storage Temperature Range		T_{stg}	-55 to 150	°C

Electrical Characteristics At TA = 25°C unless otherwise specified

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =10mA	60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V, T _J =25°C			1.0	μA
		V _{DS} =48V, V _{GS} =0V, T _J =125°C			100	
Gate-to-source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±10	μA
Forward Trans conductance	g _{fs}	V _{DS} =10V, I _D =0.1A		0.24		S
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250μA	0.8	1.5	2.5	V
Drain-to-source On-resistance	R _{DS(on)}	V _{GS} =10V, I _D =0.3A		1.5	3	Ω
		V _{GS} =4.5V, I _D =0.2A		2.4	4	
CHARGES, CAPACITANCES AND GATE RESISTANCE						
Input Capacitance	C _{ISS}	V _{GS} =0V, f=1MHz, V _{DS} =10V		30.5	45	pF
Output Capacitance	C _{OSS}			5.5	10	
Reverse Transfer Capacitance	C _{RSS}			4.1	8	
Total Gate Charge	Q _{G(TOT)}	V _{GS} =10V, V _{DS} =30V, I _D =0.2A		1.12	2	nC
Gate-to-Source Charge	Q _{GS}			0.1	0.2	
Gate-to-Drain Charge	Q _{GD}			0.23	0.5	
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(ON)}	V _{GS} =10V, V _{DS} =30V, I _D =0.2A, R _G =6Ω		3	6	ns
Rise Time	t _r			5	10	
Turn-Off Delay Time	t _{d(OFF)}			14	27	
Fall Time	t _f			9	17	
BODY DIODE CHARACTERISTICS						
Forward Voltage	V _{SD}	V _{GS} =0V, I _S =1A			1	V

Typical Characteristic

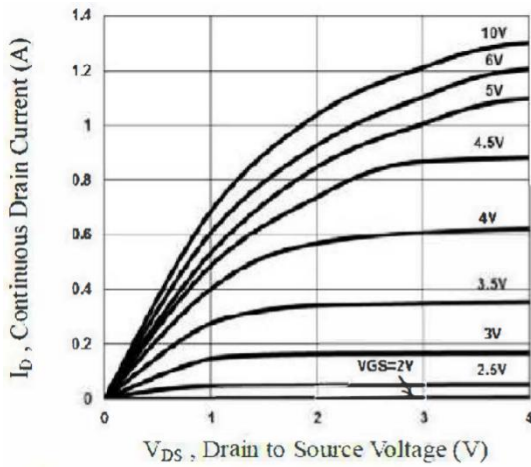


Fig.1 Output Characteristics

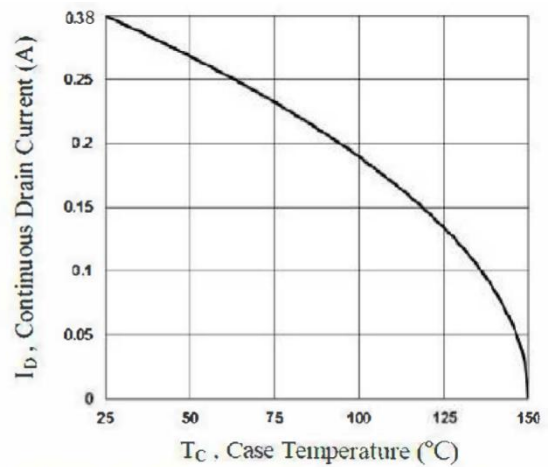


Fig.2 Continuous Drain Current vs. T_C

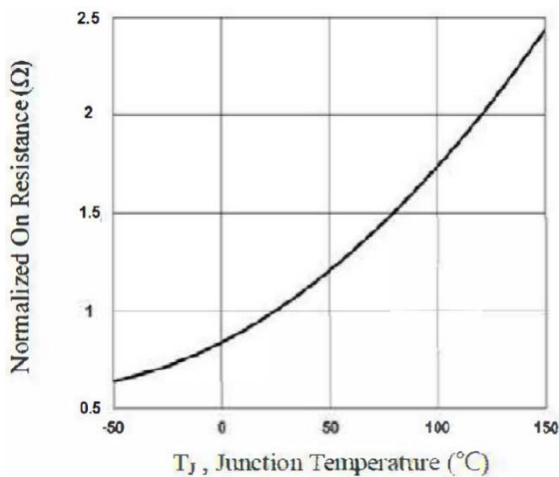


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

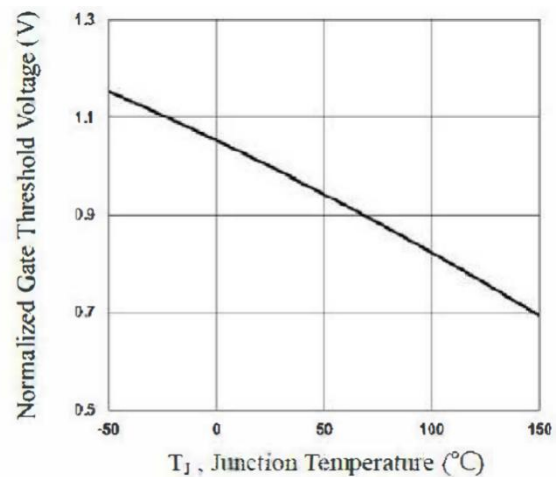


Fig.4 Normalized V_{th} vs. T_J

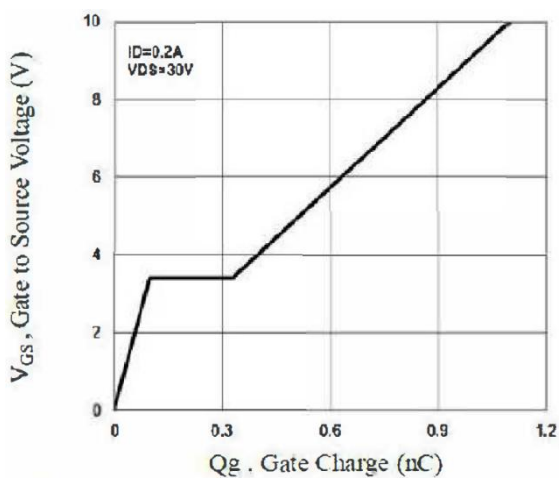


Fig.5 Gate Charge Waveform

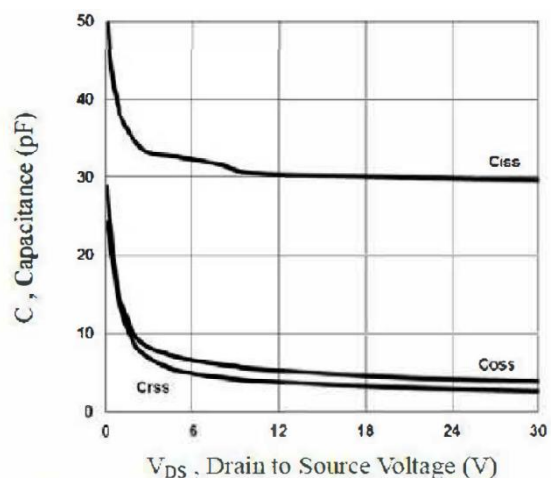


Fig.6 Capacitance Characteristics

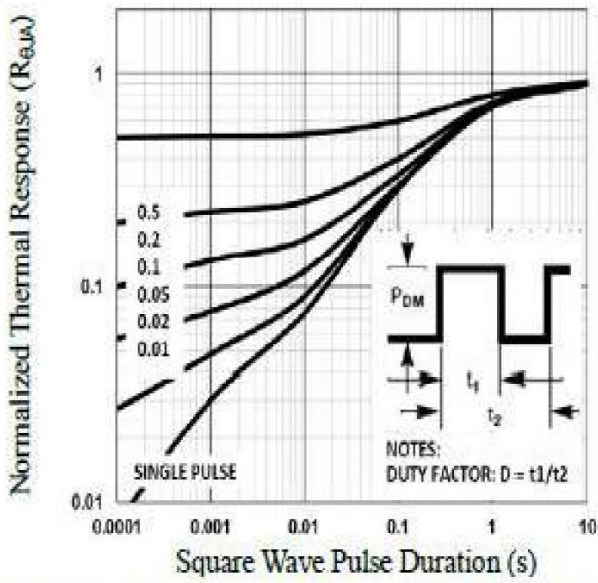


Fig.7 Normalized Transient Impedance

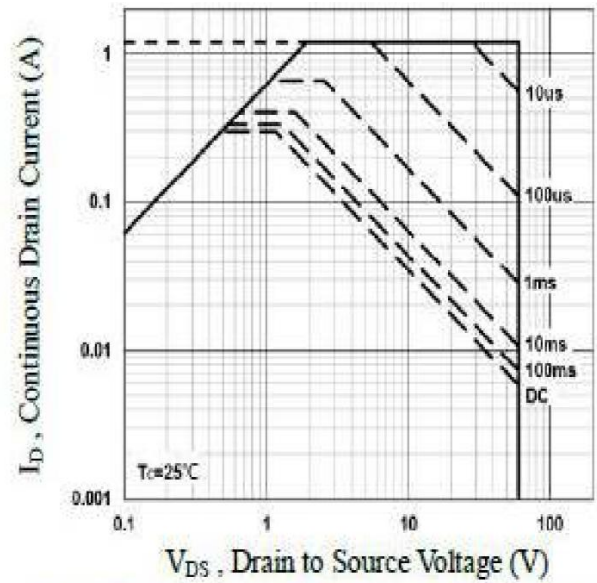


Fig.8 Maximum Safe Operation Area

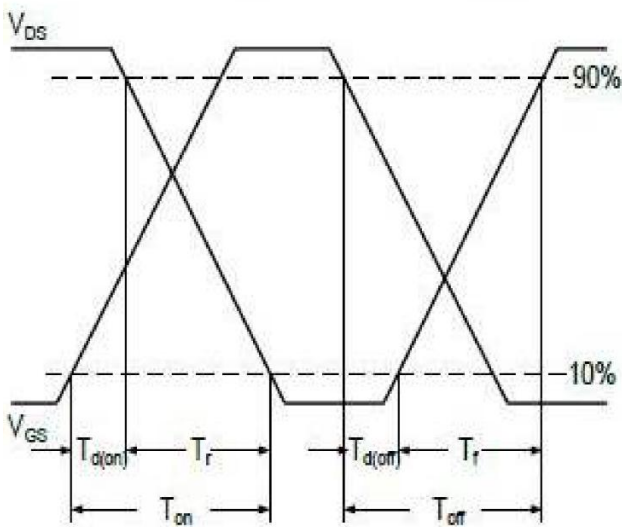


Fig.9 Switching Time Waveform

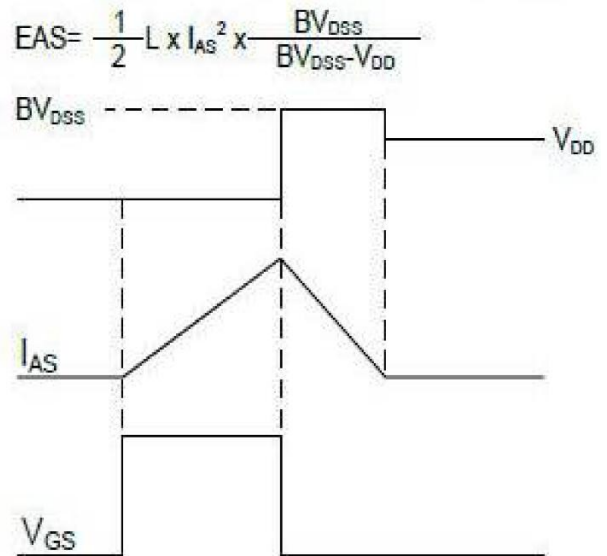
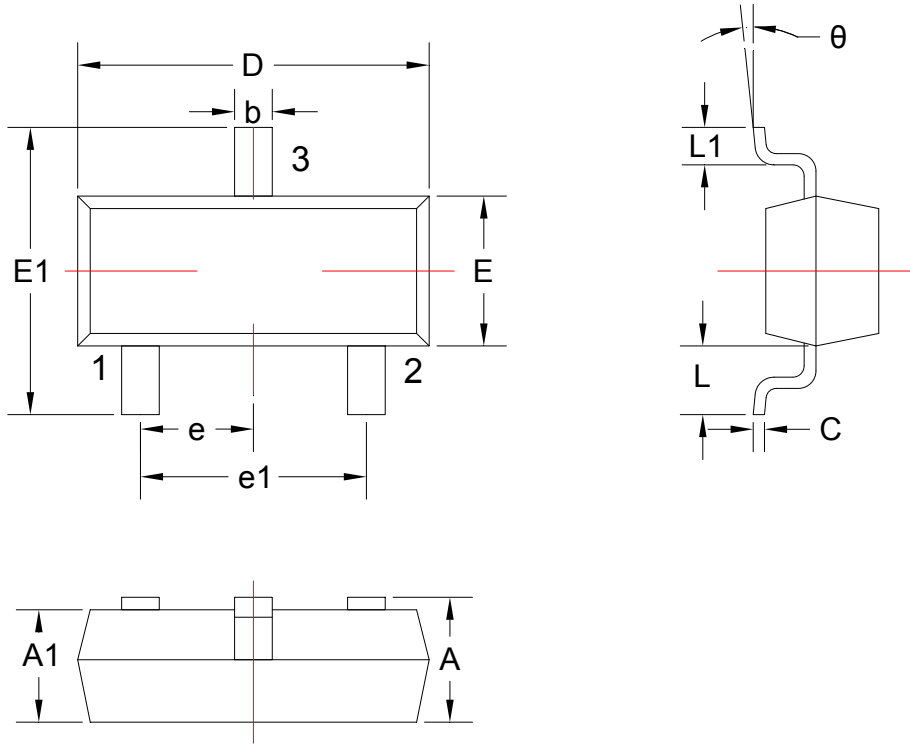
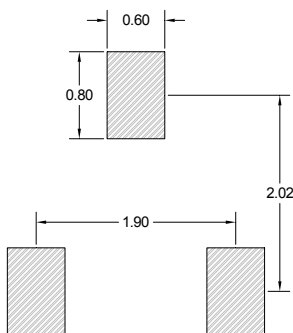


Fig.10 EAS Waveform

Dimension and Patterns (SOT-23)


Units: mm

Symbol	Dimensions		Symbol	Dimensions	
	Min.	Max.		Min.	Max.
A	0.900	1.150	E1	2.250	2.550
A1	0.900	1.050	e	0.950TYP	
b	0.300	0.500	e1	1.800	2.000
c	0.080	0.150	L	0.550REF	
D	2.800	3.000	L1	0.300	0.500
E	1.200	1.400	θ	0°	8°


Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference only
4. Unit: mm

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